

3U STRUCTURE

DESCRIPTION & MAIN FEATURES

C3S has developed a 3U CubeSat structure that uses backplane PCB for bus communication, which is intended to provide independent assembly order, simplifies the stack-up tolerances and uses space graded interface connectors. Its benefits include:

- **Flight heritage** acquired in 2021 with the launch of RadCube
- High reliability electronic, structural and thermal connections
- Access to individual cards and units during integration and testing
- Simplified stack-up tolerances
- Dedicated and independent thermal interfaces for all cards
- Radiation tested (TID)



SPECIFICATION

Physical Properties

Primary Structure Mass	752g
Secondary Structure	Depending on payload
Outside envelope (mm)	100 x 100 x 340.5

Customization

PCB stack orientation	Longitudinal (Z), Lateral (X, Y)
PCB accomodation	PC 104 USF- pattern Custom design